

# 952-D6

## Low-Solids No-Clean Liquid Flux

### Product Description

Kester 952-D6 is a no-clean, non-corrosive, halide free liquid flux that is specifically designed for the wave soldering and rework of conventional and surface mount circuit board assemblies. Essentially no residue remains after soldering. Boards are dry and cosmetically clean as they exit the wave solder machine, thus posing no interference with electrical testing. Soldering to bare copper that has been organically protected is becoming more important as manufacturers turn to surface mount technology. Kester 952-D6 was developed with a modified surface tension to aid in soldering boards that have surface mount and high component densities. This comprehensive formulation possesses improved wetting characteristics and also exhibits superior corrosion inhibiting properties and provides a non-tacky residue. A major advantage of this flux is the reduced odor associated with the soldering process.

#### Performance Characteristics:

- Residues almost colorless
- Improves soldering performance
- Reduced odor associated with soldering process
- Eliminates the need and expense of cleaning
- Non-corrosive tack-free residues
- Classified as ORL0 per J-STD-004
- Compliant to Bellcore GR-78

### RoHS Compliance

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances.

### Physical Properties

**Specific Gravity:** 0.812 ± 0.005

Antoine Paar DMA 35 @ 25°C

**Percent Solids (typical):** 3.1

Tested to J-STD-004, IPC-TM-650, Method 2.3.34

**Acid Number:** 21.4 ± 2.0 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

**pH (10% solution):** 3.1

Hanna Instruments 8314 @ 25°C

**Flash Point:** 18°C (64°F)

### Reliability Properties

**Copper Mirror Corrosion:** Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

**Corrosion Test:** Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

**Silver Chromate:** Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

**Chloride and Bromides:** None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

**Fluorides by Spot Test:** Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

**SIR, IPC (typical):** Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	<b>Blank</b>	<b>952-D6 PD</b>	<b>952-D6 PU</b>
Day 1	2.7 × 10 <sup>10</sup> Ω	2.2 × 10 <sup>10</sup> Ω	2.3 × 10 <sup>10</sup> Ω
Day 4	2.0 × 10 <sup>10</sup> Ω	1.8 × 10 <sup>10</sup> Ω	1.6 × 10 <sup>10</sup> Ω
Day 7	1.7 × 10 <sup>10</sup> Ω	1.5 × 10 <sup>10</sup> Ω	1.5 × 10 <sup>10</sup> Ω

## Application Notes

### Flux Application:

Kester 952-D6 can be applied to circuit boards by a spray, foam or dip process as well as rework of printed wire assemblies. Flux deposition should be 120-240 µg of solids/cm<sup>2</sup> (750-1500 µg of solids/in<sup>2</sup>). An air knife after the flux tank is recommended to remove excess flux from the circuit board and prevent dripping on the preheater surface.

### Process Considerations:

The optimum preheat temperature for most circuit assemblies is 90-105°C (194-221°F) as measured on the top or component side of the printed circuit board. Dwell time in the wave is typically 2-4 seconds. The wave soldering speed should be adjusted to accomplish proper preheating and evaporate excess solvent, which could cause spattering. For best results, speeds of 1.1-1.8 m/min (3½-6 ft/min) are used. The surface tension has been adjusted to help the flux form a thin film on the board surface allowing rapid solvent evaporation.

### Flux Control:

Acid number is normally the most reliable method to control the flux concentration of low solids, no clean fluxes. To check concentration, a simple acid-base titration should be used. PS-20 Test Kit and procedure are available from Kester. Control of the flux in the foam flux tank during use is necessary for assurance of consistent flux distribution on the circuit boards. The complex nature of the solvent system for the flux makes it imperative that Kester 4600 Thinner be used to replace evaporative losses. Titration is the recommended means for determining the relative flux concentration and adding the proper amount of thinner to replace evaporative losses. When excessive debris from circuit boards, such as board fibers and from the air line build up in the flux tank, these particulates will redeposit on the circuit boards which may create a build up of residues on probe test pins. It is, therefore, necessary to clean the tank and then replenish it with fresh flux when excessive debris accumulates in the flux tank.

### Cleaning:

Kester 952-D6 flux residues are non-conductive, non-corrosive and do not require removal in most applications. If residue removal is required, call Kester Technical Support.

### Storage and Shelf Life:

Kester 952-D6 is flammable. Store away from sources of ignition. Shelf life is 3 years from date of manufacture when handled properly and held at 10-25°C (50-77°F).

### Health & Safety:

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

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